

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A method of forming a battery enabled flexible circuit, the method comprising:
 - forming a first insulating layer;
 - positioning at least one battery on the first insulating layer, the at least one battery having at least first and second terminals; and
 - forming a second insulating layer on the first insulating layer and the at least one battery, the first and second insulating layers forming a flexible circuit board.
2. (Original) The method of claim 1 further comprising:
 - forming a conductive layer on the first insulating layer for providing at least first and second conductive paths, wherein at least one of the first and second terminals of the at least one battery is in electrical contact with at least one of the first and second conductive paths respectively; and
 - forming vias in the second insulating layer, the vias being in electrical contact with at least one of the first and second terminals.
3. (Original) The method of claim 2, wherein the forming the conductive layer further comprises forming a conductive layer including copper or a copper alloy.
4. (Original) The method of claim 1, wherein positioning the at least one battery further comprises forming the at least one battery on the first insulating layer using a lamination process.
5. (Currently Amended) The method of claim 1, wherein positioning the at least one battery further comprises forming the at least one battery on the first insulating layer using a semiconductor fabrication process, wherein the semiconductor fabrication process is at least one

of a process selected from the group comprising deposition, epitaxy, etch, lithography, and anneal.

6. (Original) The method of claim 1, wherein positioning the at least one battery further comprises removing a portion of the first insulating layer for embedding the at least one battery therein.

7. (Original) The method of claim 6, wherein embedding the at least one battery further comprises positioning the at least one battery in the removed portion using a lamination process.

8. (Currently amended) The method of claim 6, wherein embedding the at least one battery further comprises forming the at least one battery in the removed portion using a semiconductor fabrication process, wherein the semiconductor fabrication process is at least one of a process selected from the group comprising deposition, epitaxy, etch, lithography, and anneal.

9. (Original) The method of claim 6, wherein embedding the at least one battery further comprises embedding a preformed flexible battery in the removed portion.

10. (Original) The method of claim 1 further comprising forming the at least one battery on the second insulating layer.

11. (Original) The method of claim 1, wherein the forming the first and second insulating layers further comprises forming the first and second insulating layers using a resilient material.

12. (Original) The method of claim 1, wherein forming the first and second insulating layers further comprises forming the first and second insulating layers using a lamination process.

13. (Original) The method of claim 12 further comprising forming the first and/or second insulating layer using a polyimide material.

14. (Original) The method of claim 1, wherein forming the first and second insulating layers further comprises forming the first and second insulating layers using sputter deposition of a polyimide material.

15. (Original) The method of claim 1, wherein forming the first and second insulating layers further comprises forming the first and second insulating layers using chemical vapor deposition of a polyimide material.

16. (Original) The method of claim 1 further comprising forming the first and second insulating layers on a flexible substrate formed using a semiconductor or fiberglass material.

17. (Original) The method of claim 1 further comprising forming electrical components on the second insulating layer.

18. (Original) The method of claim 1, wherein the positioning the at least one battery further comprises positioning a thin-film flexible battery.

19. (Original) The method of claim 2 further comprising removing a portion of the conductive layer using a semiconductor fabrication process and embedding a flexible battery therein.

20. (Original) The method of claim 19, wherein the using the semiconductor fabrication process further comprises etching.

21. (Original) The method of claim 1 further comprising positioning a plurality of batteries in a single conductive layer.

22. (Original) The method of claim 1 further comprising positioning at least one battery in each of a plurality of insulating and conductive layers for providing multiple power sources.

23-41. (Canceled)